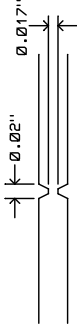
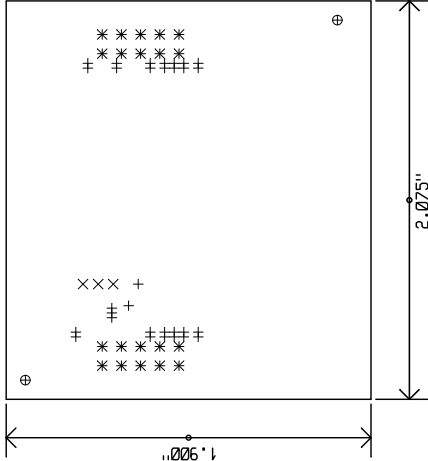


REVISION HISTORY			
ECO	REV	DESCRIPTION	APPROVED
-	1	1ST PROTOTYPE	KEITH B.
			DATE
			12-2-10

NOTES: UNLESS OTHERWISE SPECIFIED

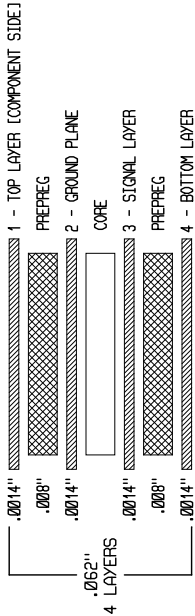
1. FAB PER IPC-A-600
2. MATERIAL: -EPOXY FIBERGLASS, NEMA GRADE FR-4
-FINISHED THICKNESS TO BE 0.062" +/- .005"
-TOTAL OF 4 LAYERS WITH 1 OZ. CU ON THE OUTER LAYERS
AND 1 OZ. CU ON THE INNER LAYERS
-FLAMMABILITY RATING: 94V-0 MINIMUM
3. SIZE: CUT TO DIMENSIONS AND TOLERANCES SHOWN
4. DRILLING: -DRILL HOLES PER SCHEDULE, PLATE THROUGH HOLES WITH COPPER, 0.001" THICK MIN.
-ALL HOLE SIZES ARE SPECIFIED AFTER PLATING
-HOLE LOCATION TOLERANCES ARE +/- 0.003" IN RELATION TO CENTER
5. FINISH: -SPOBC USING LPI BOTH SIDES, COLOR GREEN
-GOLD IMMERSION BOTH SIDES
-FOR SILKSCREEN: TOP SIDE USE WHITE NON-CONDUCTIVE INK (LEAD FREE SOLDER MAY BE USED FOR PROTOTYPE)
6. DO NOT ALTER ARTWORK e.g. TO ADD LOGO OR DATE CODE. PAD SIZE MAY BE MODIFIED TO MEET END FINISH.
7. PCBs ARE TO BE ROHS COMPLIANT
8. DESIGN HAS SOLDER MASK DEFINED PADS ON U1.
U1 SOLDER MASK SIZE IS 25 MIL AND PAD SIZE IS 29 MIL. DO NOT CHANGE ANY SIZE ON THIS COMPONENT.
9. SCORING FOR PANELIZED PCB:

SHOWN FROM COMPONENT SIDE



SIZE	QTY	SYM	PLATED	TOL
0.010"	31	+	YES	+/-0.003"
0.032"	3	X	YES	+/-0.003"
0.040"	20	*	YES	+/-0.003"
0.070"	2	⊕	NO	+/-0.003"

LAYER STRUCTURE



UNLESS OTHERWISE SPECIFIED		APPROVALS	
DIMENSIONS ARE IN INCHES TOLERANCES: 0.XX" = +/- 0.01" 0.XXX" = +/- 0.005" INTERPRET DIM AND TOL PER ASME Y14.5M-1994	PCB DES.	KEITH B.	
	APP ENG.	KEITH B.	
	INTERPRET DIM AND TOL PER ASME Y14.5M-1994		
THIRD ANGLE PROJECTION			
SCALE = 1:1			
DATE: Thursday December 2, 2010			
SHEET 1 OF 1			

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Fax: (408) 434-0507
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TITLE: SCHEMATIC
SPT/DIGITAL OR I2C UNMODULE ISOLATOR, LOW EMI

SIZE: N/A
IC NO.: LTM2886CV-35/-55/-31/-51
DEMO CIRCUIT 1790A

REV. 1